

T11

无机镀层水溶型助焊剂



介绍

T11是一种无机酸性助焊剂，它是活性非常强的锌铵类助焊剂。T11是一种无烟、不易燃的水溶性助焊剂，特别设计应用在侵焊工艺中恢复受污染铜表面的可焊性。镀锡的焊盘或其它金属盘表面优点在于有一种很厚的，无机的无空洞表层，合金层通过基础金属形成。Asahi的创新技术已经使T11在热侵焊工艺中得到了发展应用。助焊剂残余物可以通过水洗完全冲刷干净，从而去除铜线表层的离子污染。

应用

铜线首先通过含有T11的助焊剂罐，添加助焊剂之后，在进行镀锡工艺之前不需要进行预热，并且铜线表面通过湿布擦拭很容易清洁。

残余处理

焊接后的残余物是吸潮物质和离子化合物，在焊接后立即进行所有残余物的清理是必要的。残余物的清洁先在水温不低于40度时用水进行冲洗，之后再通过去离子水进行冲洗。

稀释剂

不需要稀释剂。

健康 & 安全

遵循使用处理准则，如：装置良好的通风系统及避免长久持续与皮肤接触。如需要更多资讯，请参看材料安全资料表。

存储

T11在良好的储存环境中可存放长达6个月之久。

包装

25公斤容器。

规格

测试	测试成绩
状态	液体
颜色	无色的
比重 @ 25°C	1.015 +/- 0.005
JIS Z 3197 8.2.2	
含固量 (110°C, 3小时)	2.5 +/- 0.3 wt%
JIS Z 3197 8.1.3	
卤化物含量	1.7 +/- 0.3 wt%
JIS Z 3197 8.1.4.2.1	
pH	< 2
扩散率	> 80% (SnPb)
JIS Z 3197 8.3.1.1	
焊点外观	光亮

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